THE DATASHEET OF

MMST3904Q-7-F

www.win-source.net 0086-755-83957316

40V NPN SMALL SIGNAL TRANSISTOR IN SOT323

Features

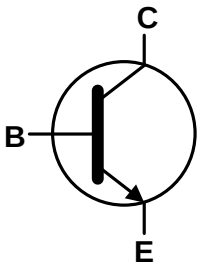
- BV_{CEO} > 40V
- I_C = 200mA Collector Current
- Epitaxial Planar Die Construction
- Ultra-Small Surface Mount Package
- Complementary PNP Type: MMST3906
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**
- **Qualified to AEC-Q101 Standards for High Reliability**

Mechanical Data

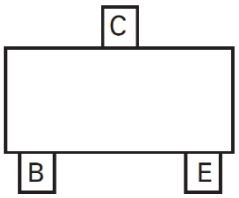
- Case: SOT323
- Case Material: Molded Plastic. "Green" Molding Compound. UL Flammability Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish - Matte Tin Plated Leads, Solderable per MIL-STD-202, Method 208 e3
- Weight: 0.006 grams (Approximate)

SOT323

Top View



Device Symbol



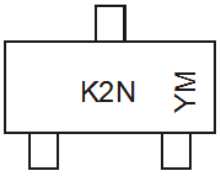
Pin-out Top View

Ordering Information (Note 4)

Part Number	Compliance	Marking	Reel Size (inches)	Tape Width (mm)	Quantity Per Reel
MMST3904-7-F	Standard	K2N	7	8	3,000

Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

Marking Information



K2N = Product Type Marking Code
YM = Date Code Marking
Y or $\overline{Y}$ = Year (ex: G = 2019)
M or $\overline{M}$ = Month (ex: 9 = September)

Date Code Key

Year	2018	2019	2020	2021	2022	2023	2024	2025	2026	2027	2028
Code	F	G	H	I	J	K	L	M	N	O	P

Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	O	N	D

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Absolute Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V_{CBO}	60	V
Collector-Emitter Voltage	V_{CEO}	40	V
Emitter-Base Voltage	V_{EBO}	6	V
Collector Current	I_C	200	mA

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 5)	P_D	200	mW
Thermal Resistance, Junction to Ambient (Note 5)	$R_{\theta JA}$	625	°C/W
Operating and Storage Temperature Range	T_J, T_{STG}	-55 to +150	°C

ESD Ratings (Note 6)

Characteristic	Symbol	Value	Unit	JEDEC Class
Electrostatic Discharge - Human Body Model	ESD HBM	4,000	V	3A
Electrostatic Discharge - Machine Model	ESD MM	400	V	C

Notes: 5. For a device mounted with the collector lead on minimum recommended pad layout 1oz copper that is on a single-sided 1.6mm FR-4 PCB; device is measured under still air conditions whilst operating in a steady-state.
6. Refer to JEDEC specification JESD22-A114 and JESD22-A115.

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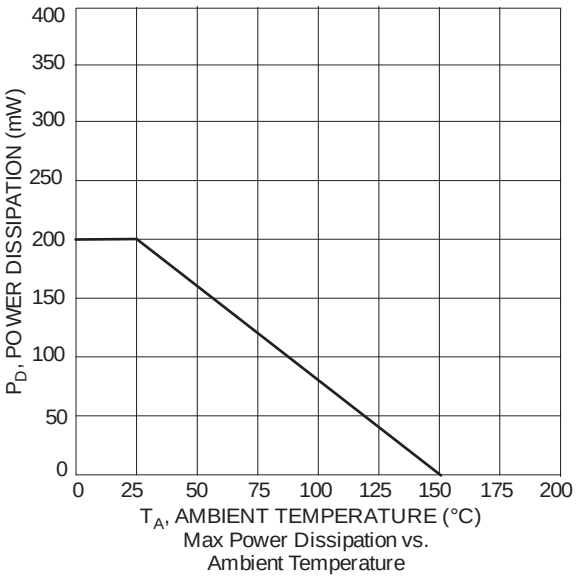
Thermal Characteristics and Derating Information



Max Power Dissipation vs.
Ambient Temperature

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Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 7)					
Collector-Base Breakdown Voltage	BV_{CBO}	60	—	V	I_C = 10μA, I_E = 0
Collector-Emitter Breakdown Voltage	BV_{CEO}	40	—	V	I_C = 1mA, I_B = 0
Emitter-Base Breakdown Voltage	BV_{EBO}	5	—	V	I_E = 10μA, I_C = 0
Collector Cutoff Current	I_{CEX}	—	50	nA	V_{CE} = 30V, $V_{EB(OFF)}$ = 3V
Base Cutoff Current	I_{BL}	—	50	nA	V_{CE} = 30V, $V_{EB(OFF)}$ = 3V
ON CHARACTERISTICS (Note 7)					
DC Current Gain	h_{FE}	40 70 100 60 30	— — 300 — —	—	I_C = 100μA, V_{CE} = 1V I_C = 1mA, V_{CE} = 1V I_C = 10mA, V_{CE} = 1V I_C = 50mA, V_{CE} = 1V I_C = 100mA, V_{CE} = 1V
Collector-Emitter Saturation Voltage	$V_{CE(SAT)}$	—	0.25 0.30	V	I_C = 10mA, I_B = 1mA I_C = 50mA, I_B = 5mA
Base-Emitter Saturation Voltage	$V_{BE(SAT)}$	0.65 —	0.85 0.95	V	I_C = 10mA, I_B = 1mA I_C = 50mA, I_B = 5mA
SMALL SIGNAL CHARACTERISTICS					
Output Capacitance	C_{obo}	—	4	pF	V_{CB} = 5V, f = 1.0MHz, I_E = 0
Input Capacitance	C_{ibo}	—	8	pF	V_{EB} = 0.5V, f = 1.0MHz, I_C = 0
Input Impedance	h_{ie}	1	10	kΩ	V_{CE} = 10V, I_C = 1mA, f = 1.0MHz
Voltage Feedback Ratio	h_{re}	0.5	8.0	x 10^{-4}	
Small Signal Current Gain	h_{fe}	100	400	—	
Output Admittance	h_{oe}	1	40	μS	
Current Gain-Bandwidth Product	f_T	300	—	MHz	V_{CE} = 20V, I_C = 10mA, f = 100MHz
Noise Figure	NF	—	5	dB	V_{CC} = 5V, I_C = 100μA, R_S = 1kΩ, f = 1MHz
SWITCHING CHARACTERISTICS					
Delay Time	t_d	—	35	ns	V_{CC} = 3V, I_C = 10mA, $V_{BE(OFF)}$ = -0.5V, I_{B1} = 1mA
Rise Time	t_r	—	35	ns	
Storage Time	t_s	—	200	ns	V_{CC} = 3.0V, I_C = 10mA, I_{B1} = I_{B2} = 1.0mA
Fall Time	t_f	—	50	ns	

Note: 7. Measured under pulsed conditions. Pulse width ≤ 300μs. Duty cycle ≤ 2%.

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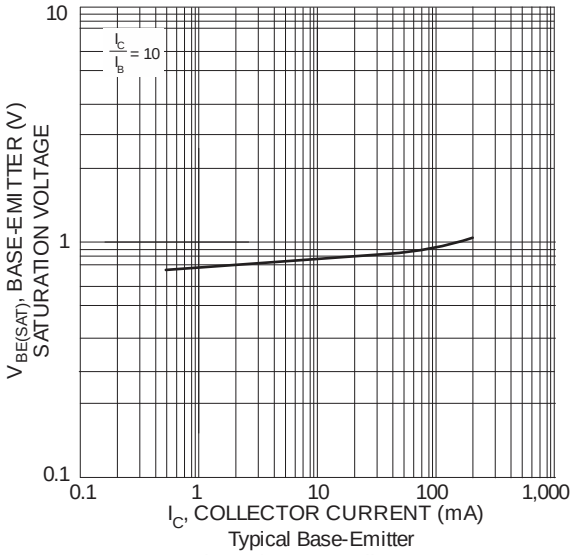
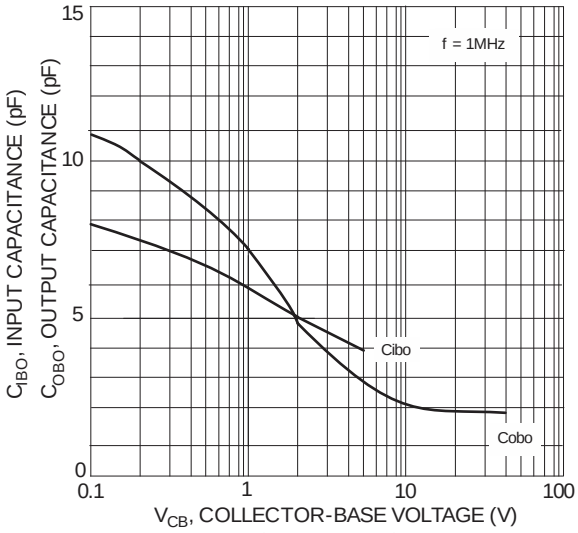
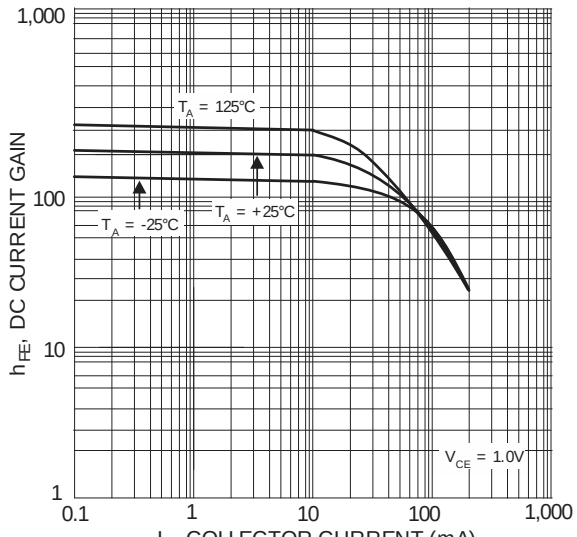
Typical Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)



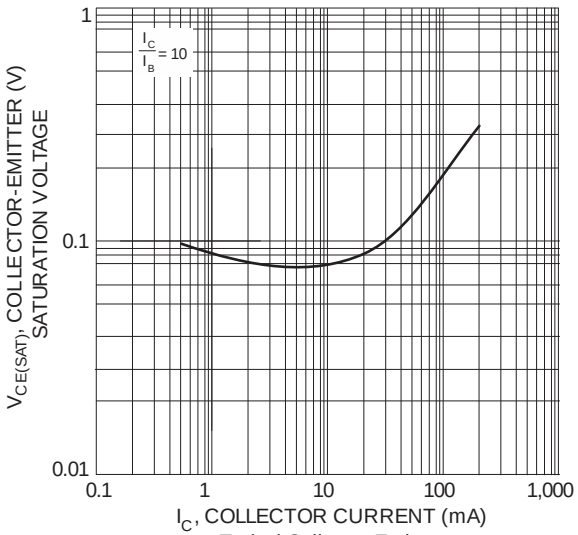
Typical Base-Emitter
Saturation Voltage vs. Collector Current



Input and Output Capacitance vs.
Collector-Base Voltage



Typical DC Current Gain vs. Collector Current



Typical Collector-Emitter
Saturation Voltage vs. Collector Current

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Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

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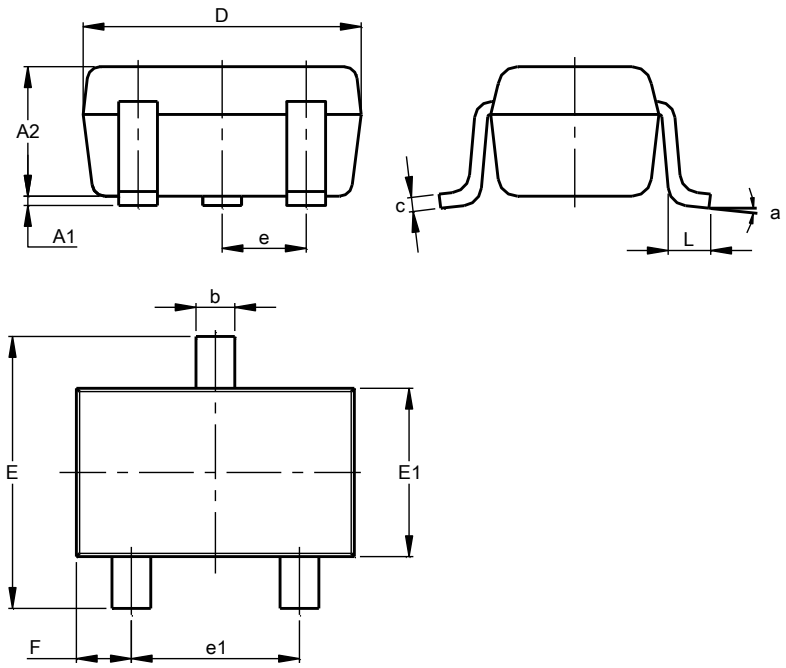
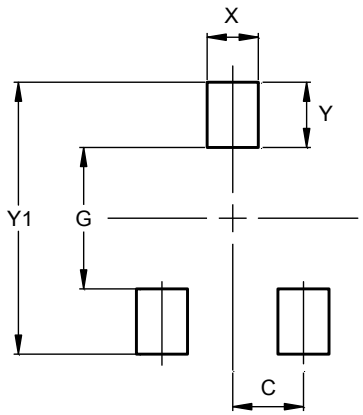


SOT323			
Dim	**Min**	**Max**	**Typ**
A1	0.00	0.10	0.05
A2	0.90	1.00	0.95
b	0.25	0.40	0.30
c	0.10	0.18	0.11
D	1.80	2.20	2.15
E	2.00	2.20	2.10
E1	1.15	1.35	1.30
e	0.650 BSC		
e1	1.20	1.40	1.30
F	0.375	0.475	0.425
L	0.25	0.40	0.30
a	0°	8°	--
All Dimensions in mm			

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

SOT323



Dimensions	Value (in mm)
C	0.650
G	1.300
X	0.470
Y	0.600
Y1	2.500

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